

产品规格书

DATA SHEET

客户名称：_____

产品名称： 单相整流桥 _____

产品型号： DB1**整流桥 _____

产品描述： 玻璃钝化芯片整流桥
1A (400-1000V) _____

物料编码： 无 _____

制作人	审核	核准

客户确认 Customer Signature

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1A 单相整流桥

特征 Features

玻璃钝化芯片

Glass passivated chip

低反向漏电流

Low Reverse Leakage Current

高耐浪涌电流能力达30安培

High surge current capability to 30Amperes

塑封料已经UL可燃性认证94V-0，UL档案编号：E496193

Plastic material has Underwriters Laboratory flammability recognition 94V-0，Recognized File # E496193

符合ROHS要求

ROHS compliance

高温焊接保证：260°C±5°C/10秒，拉力2.3 Kgf.cm

High temperature soldering guaranteed: 260°C±5°C/10 seconds (2.3 Kgf.cm)tension



机械参数 Mechanical Data

本体：塑封

Case : Molded plastic case

极性：极性符号铸在管体上

Polarity : Polarity symbols being marked on body

重量：约 0.3 克

Weight : About 0.3grams

最大额定值 Maximum Ratings Parameter @ Ta = 25°C unless otherwise noted								
名词解释	参数条件		符号	04	05	06	07	单位
反向重复峰值电压 Maximum Recurrent Peak Reverse Voltage			V_{RRM}	400	600	800	1000	V
反向不重复峰值电压 Reverse non-repetitive peak voltage			V_{RSM}	500	700	900	1100	V
最大直流电压 Maximum DC Blocking Voltage			V_{DC}	400	600	800	1000	V
平均整流输出电流 Average Rectified Output Current	50Hz 正弦波负载, 50Hz sine wave load	$T_a=40^{\circ}C$	$I_{(AV)}$	1				A
最大正向浪涌电流 Peak Surge Forward Current	50HZ 正弦波,一个周期, $T_j=25^{\circ}C$ 50HZ sine wave,1 cycle, $T_j=25^{\circ}C$		I_{FSM}	30				A
热容值 Rating for fusing	1ms<t<8.3ms, $T_j=25^{\circ}C$, 单个二极管 1ms<t<8.3ms, $T_j=25^{\circ}C$, Rating of per diode		I^2t	3.7				A ² s
结温 Junction temperature			T_J	-55 ~ +150				°C
存储温度 Storage Temperature			T_{STG}	-55 ~ +150				°C
电性特性 Electrical Characteristics (Ta=25°C Unless otherwise specified)								
正向峰值电压 Peak Forward Voltage	IF=0.5A, 脉冲测试, 单个二极管的额定值 IF=0.5A,Pulse measurement, Rate of per diode	$T_a=25^{\circ}C$	V_F	1				V
反向峰值电流 Peak Reverse Current	VR=VRRM, 脉冲测试, 单个二极管的额定值 VR=VRRM, Pulse measurement Rating of per diode	$T_j=25^{\circ}C$	I_{RRM}	5				μA
		$T_j=125^{\circ}C$		500				
热阻 Thermal resistance	结到环境的热阻,无散热片 Junction to ambient, without heatsink		$R_{\theta J-A}$	68				°C/W

特性曲线

FIG.1 . Derating Curve For Output Rectified Current

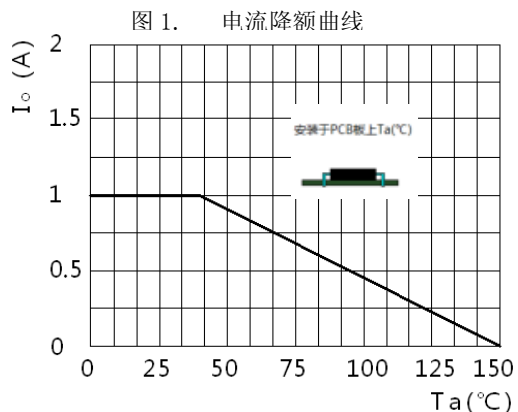


FIG.2 . Maximum Non-Repetitive Peak Orward Surge Current Per Bridge Element

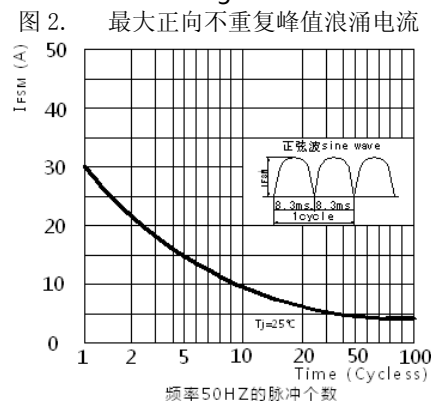


FIG3. Typical Reverse Characteristics Per Bridge Element

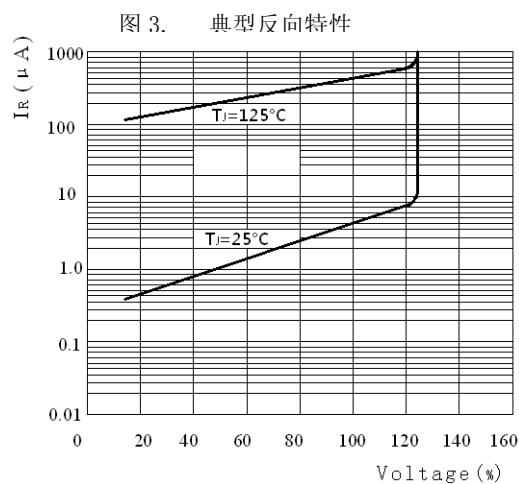
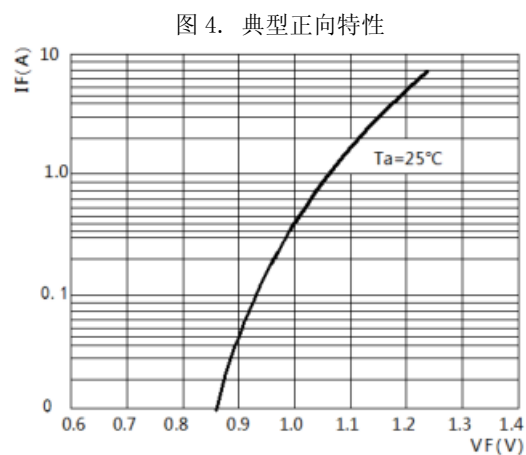
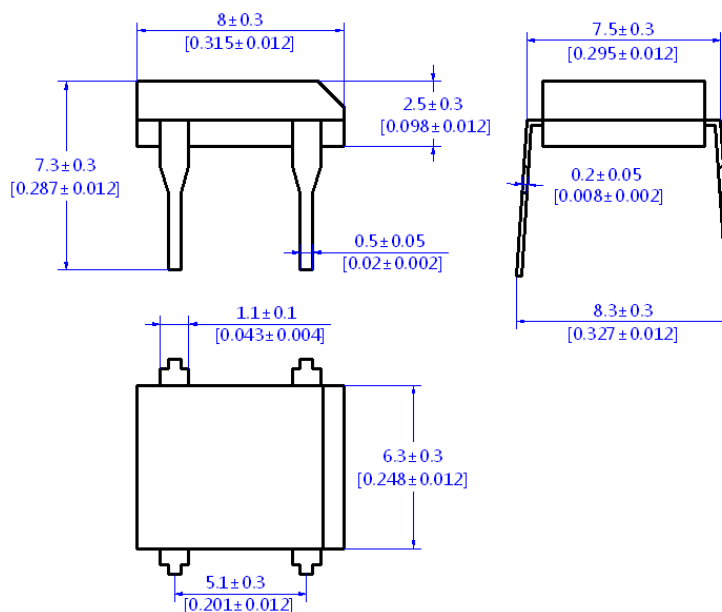


FIG4. Typical Forward Characteristics Per Bridge Element



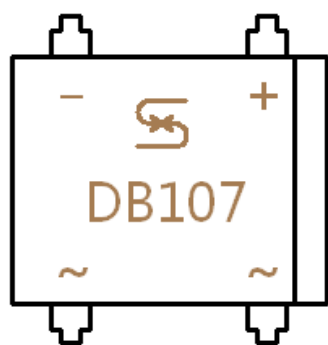
尺寸图 Dimensioned drawing



Dimensions in millimeters and inches

外形图

Outside view



DB 1 **

- **为反向峰值电压,核算公式=数值*100
- 1表示电流1A
- DB表示封装代码